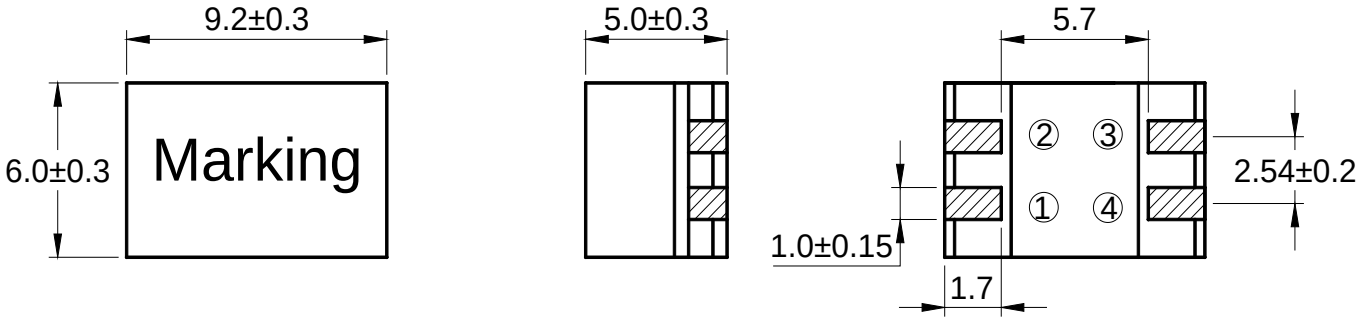
Outline:
产品概要

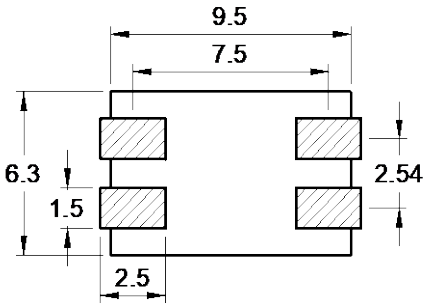
- Excellent impedance characteristics, making it great for suppressing common mode noise.
  高阻抗特性，能高效抑制共模噪音效果。
- Low profile design makes it optimal for surface mounting.
  因低的高度设计，适合表面安装。
- Current compensated surface mount common mode chokes for controller area networks (CAN-Bus) in automotive, industrial and medical applications.
  用于汽车、工业和医疗应用的控制器局域网(CAN-Bus)的电流补偿表面安装共模扼流圈。
- Operating temperature : -40℃ ～ +125℃
  (Including coil's temperature rise)
  工作温度：-40℃～+125℃（包含线圈发热）

1 Appearance and Dimensions (mm)
外形尺寸 (mm)

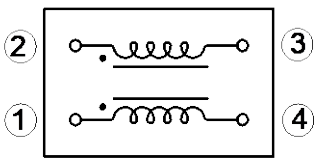


2 Marking
印字标识

3 Reference Land Pattern (mm)
参考基板尺寸 (mm)



4 Schematic
原理图



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5 Electrical Characteristics
电气特性

Part No. 型 号	Inductance (μH) 电感值	Impedance (Ω) 阻抗值※1	Leakage Inductance (nH) 漏感※2	D.C.R (mΩ) 直流电阻	Rated Current (A) 额定电流※3	Rated Voltage (V) 额定电压	Frequency Range (MHz) 频率范围
		Min	Typical	Max	Max	Max	
CSTR0950B-100	10.0±30%	200	40.0	70.0	1.60	80.0	20.0~300
CSTR0950S-100	10.0±30%	200	800	70.0	1.60	80.0	20.0~300
CSTR0950B-250	25.0±30%	600	150	110	1.00	80.0	20.0~150
CSTR0950S-250	25.0±30%	600	1,000	110	1.00	80.0	20.0~150
CSTR0950B-400	40.0±30%	800	220	250	0.90	80.0	20.0~100
CSTR0950S-400	40.0±30%	800	1,500	250	0.90	80.0	20.0~100
CSTR0950B-510	51.0±30%	1,000	220	160	1.00	80.0	20.0~100
CSTR0950S-510	51.0±30%	1,000	1,900	160	1.00	80.0	20.0~100
CSTR0950B-251	250±50%	600	120	130	1.20	80.0	3.00~20.0
CSTR0950B-501	500±50%	1,000	220	150	1.00	80.0	1.00~20.0
CSTR0950B-102	1,000±50%	1,500	250	310	0.80	80.0	1.00~15.0
CSTR0950B-202	2,000±50%	3,000	350	420	0.60	80.0	1.00~5.00
CSTR0950B-472	4,700±50%	4,000	550	750	0.50	80.0	0.30~3.00
CSTR0950B-652	6,500±50%	5,000	800	950	0.40	80.0	0.30~2.00

■ All data is tested based on 25℃ ambient temperature.
所有数据基于环境温度 25℃条件下测试。

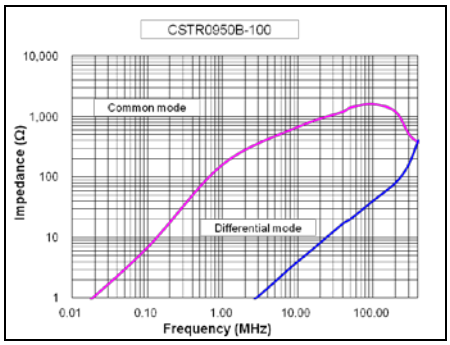
※1 Impedance measure condition reference frequency range.
共模阻抗测试条件参考频率范围。

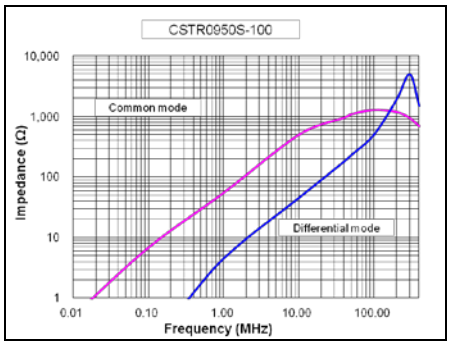
※2 Leakage inductance is for L1 and is measured with L2 shorted.
漏感：在短路 L2 绕组的前提下测试 L1 绕组所得的电感。

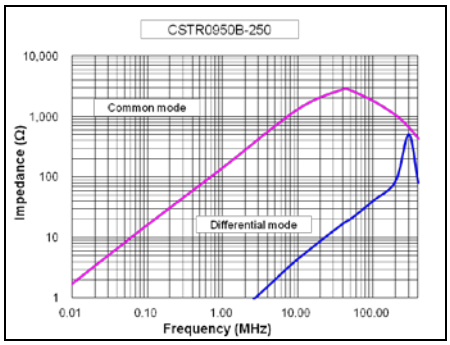
※3 Rated current：the value of DC current when the temperature rise is ΔT40℃(Ta=25℃).
额定电流：使产品温度上升到 ΔT40℃时所加载的直流电流值(Ta=25℃)。

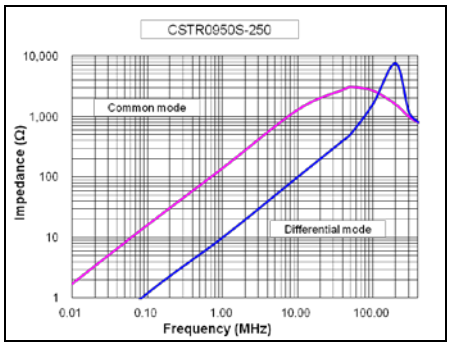
※ Special remind：Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒：线路设计，组件布局，印刷线路板(PCB)尺寸及厚度，散热系统等均会影响产品温度。
请务必在最终应用时，验证产品发热状况。

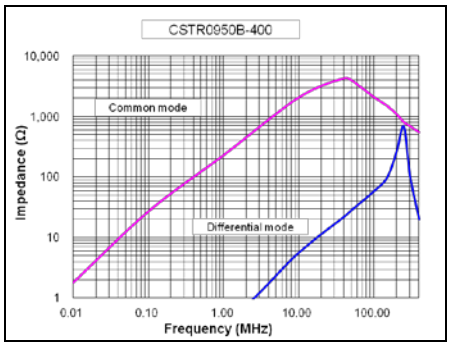
6 Impedance vs Frequency Curve
阻抗值 VS 频率曲线

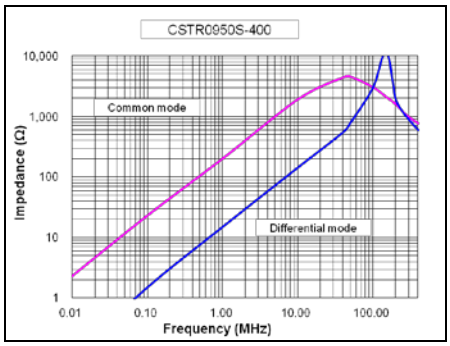


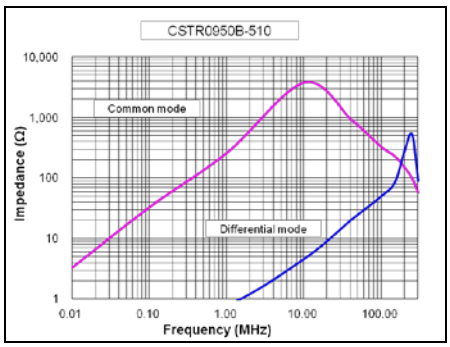


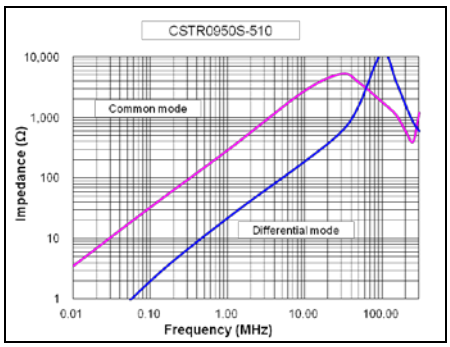


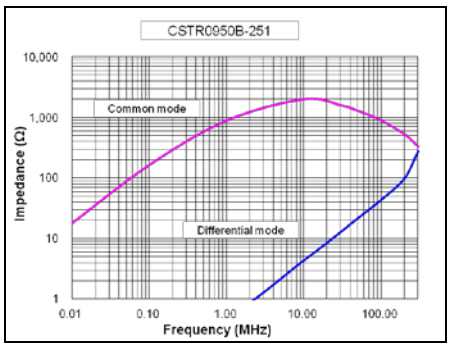


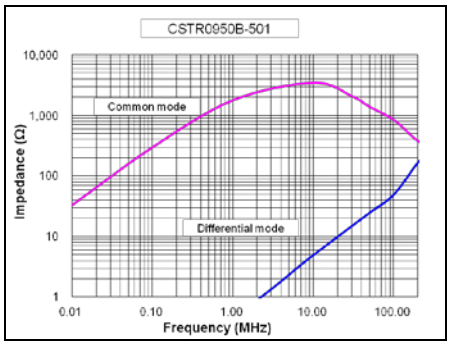


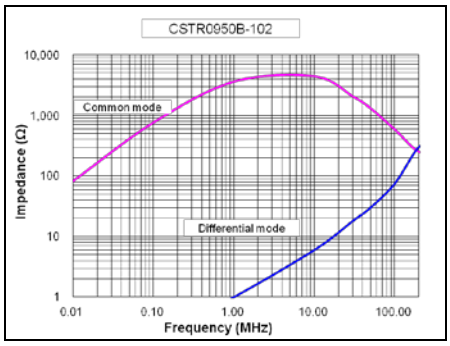


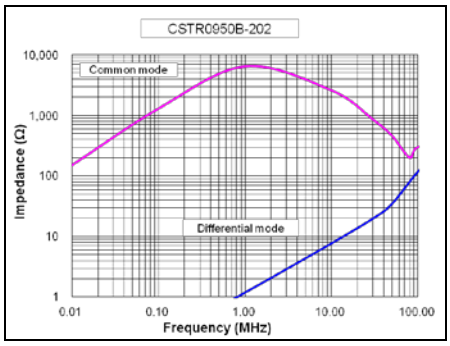


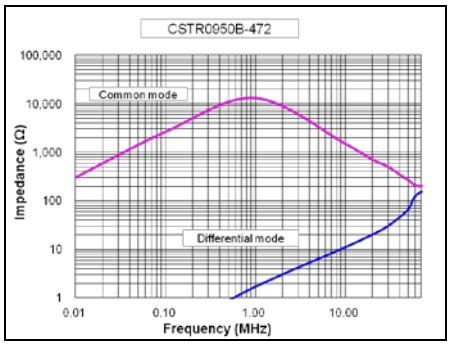


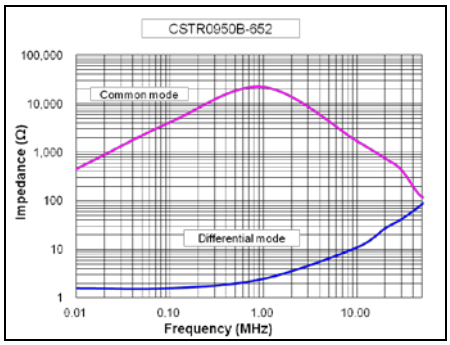






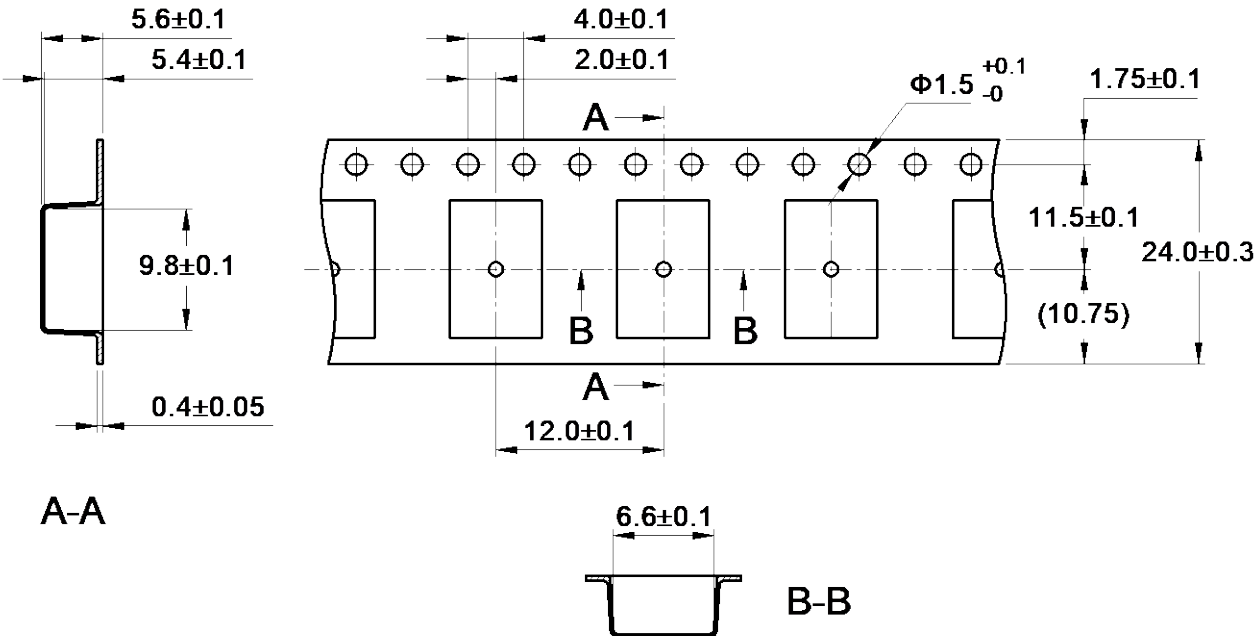



CSTR0950B-472
100,000
10,000
1,000
100
10
1
Impedance (Ω)
Common mode
Differential mode
0.01
0.10
1.00
10.00
Frequency (MHz)


CSTR0950B-652
100,000
10,000
1,000
100
10
1
Impedance (Ω)
Common mode
Differential mode
0.01
0.10
1.00
10.00
Frequency (MHz)

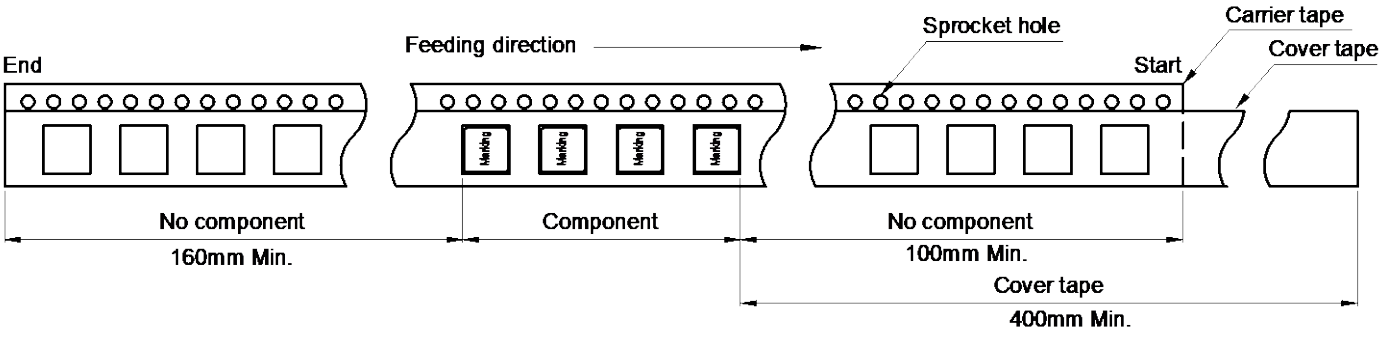
7 Packing Specification
包装规格

7.1 Carrier Tape Dimensions (mm)
载带尺寸



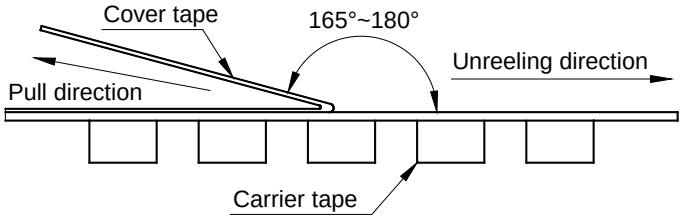
※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction
捆包方向

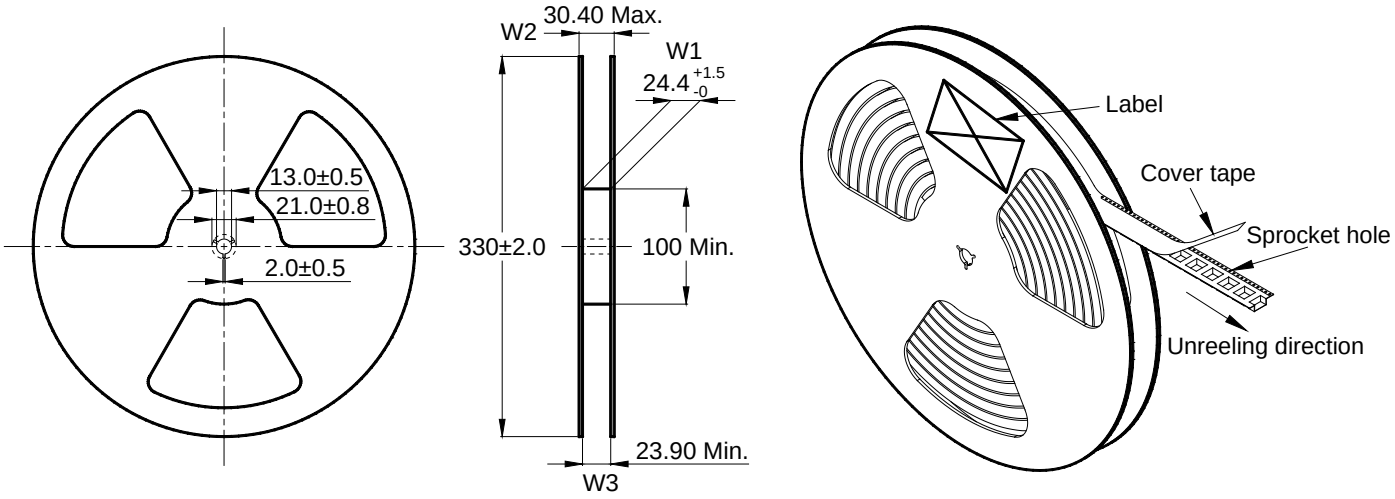


7.3 Cover Tape Peel Off Condition
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
  盖带剥离力度为 0.1～1.3N。
- Reference peel speed 300±10mm/min.
  参考剥离速度 300±10mm/分钟。



7.4 Reel Dimensions (mm)
卷盘尺寸(mm)



7.5 Carton Dimensions and Packing Quantity
包装箱尺寸和包装数量

■ Inner Carton：340×340×95mm
内包装盒

■ Out Carton ： 355×355×385mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSTR0950	1000pcs	(1000×2) = 2000pcs	(2000×3) = 6000pcs

7.6 Label Making
标签标识

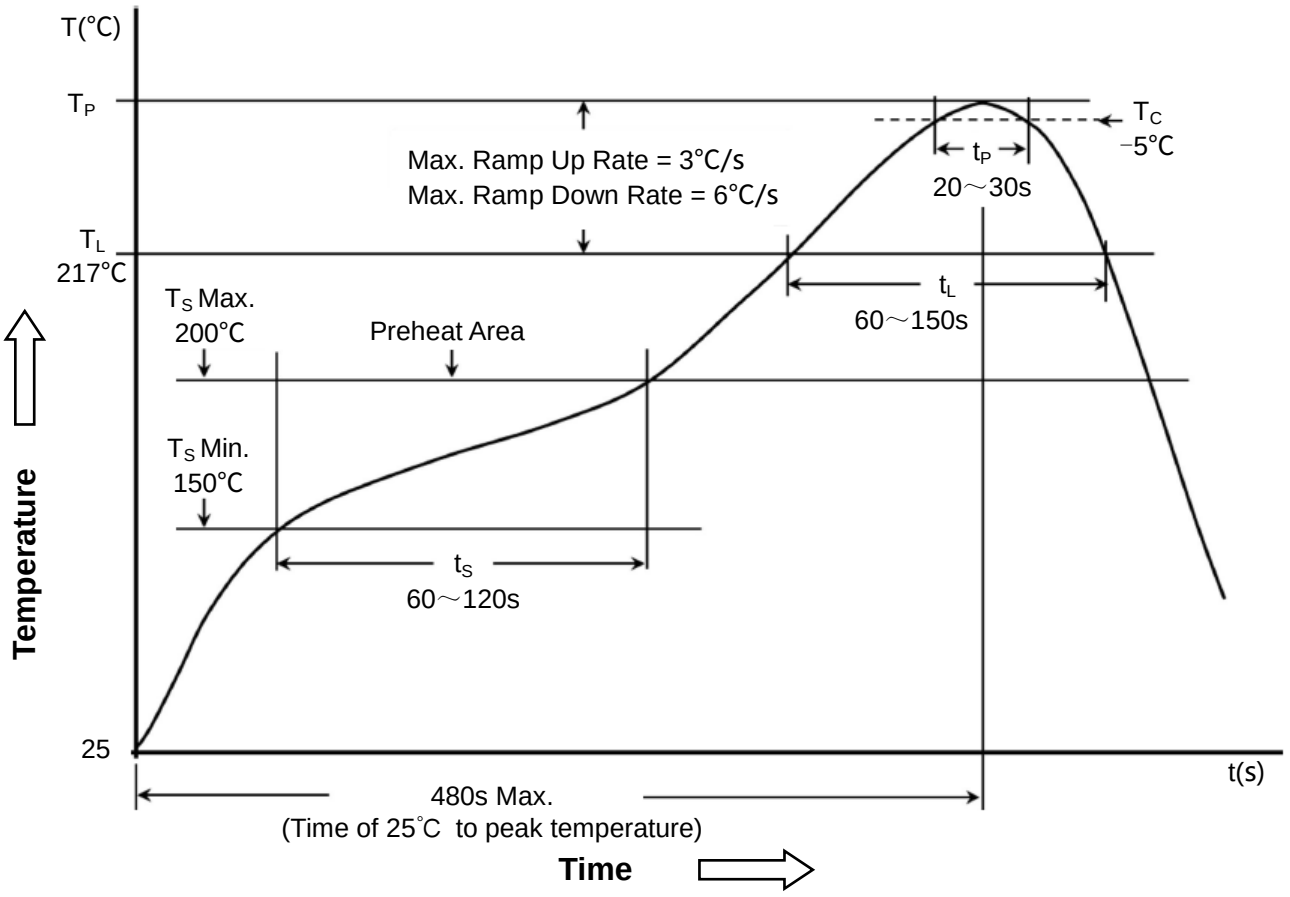
The following items will be marked on the tray of product label and shipping label.
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

Production Label
产品标签
- ■ Packing No.
  包装流水号
- ■ Quantity
  数 量
- ■Shipment Date
  出货日期
- ■ Part No.
  产品型号
- ■Customer Part No.
  客户型号
- ■ Customer Po No.
  客户订单号

Shipping Label
运输标签
- ■ Packing No.
  包装流水号
- ■ Quantity
  数 量
- ■Shipment Date
  出货日期
- ■ Part No.
  产品型号
- ■Customer Part No.
  客户型号
- ■ Customer Po No.
  客户订单号

8 Soldering Specification
焊接规格

8.1 Reflow Profile for SMT Components
SMT 回流焊温度曲线



8.2 Classification of Peak Package Body Temperature (T_P)
封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm^3	350～2000 mm^3	>2000 mm^3
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6～2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。